

**Endicott Interconnect Technologies, Inc.
Fact Sheet**

<http://endicottinterconnect.com>

Endicott Interconnect Technologies, Inc. is a world leader in the delivery of innovative electronics manufacturing services.

Business	Endicott Interconnect is a vertically integrated provider of high-performance electronics packaging solutions to OEMs in a variety of markets. The Company offers a broad range of products and services, including printed circuit board fabrication, semiconductor packaging and complex assembly solutions. Its services include design, first and second level assembly, integration of complex electronic equipment and comprehensive advanced lab services.
Customers	The Company has added numerous customers since its inception. Customers include IBM, Sun, Hutchinson, Cadence, Juniper, Cisco, Verigy, Boeing, Northrop Grumman, Raytheon and the U.S. Defense Department.
Markets Served	Endicott Interconnect is focused on solutions for mission critical and high-performance applications such as those found in the defense and aerospace, communications and computing, semiconductor, advanced test equipment and medical markets.
Manufacturing Operations	Endicott Interconnect currently operates in 1.39 million square feet of manufacturing space in Endicott, NY and has manufacturing operations for high volume production capacity in Shenzhen, China.
Corporate Headquarters	Endicott, New York
Differentiating Technologies	Endicott Interconnect is a global provider of innovative products and solutions for the electronics industry which is differentiated by its technology. The Company's technological expertise and proprietary materials science are the principal drivers of its success. The Company has developed organic substrates that are lighter, smaller and more reliable than the traditional ceramic substrates. These capabilities are an important competitive advantage in its principal markets where customers seek to minimize the weight of electronic equipment and provide as much functionality as possible in increasingly smaller spaces without sacrificing performance or reliability. The Company continues to enhance its technological advantage by investing in research and development and growing its research collaborations with universities and customers.